

ABSTRACT

According to one embodiment, a wafer (10) includes a substrate (11) including a first region (RA) and a second region (RB) that do not overlap each other; a first chip unit and a second chip unit (100) each arranged on the substrate; a first electrode (16A) and a second electrode (16B) each electrically connected to the first chip unit; and a third electrode (16A) and a fourth electrode (16B) each electrically connected to the second chip unit. The first electrode and the third electrode are arranged in the first region. The second electrode and the fourth electrode are arranged in the second region. The first region is independent of a region in which the first chip unit and the second chip unit are provided.